

Docket No.: 4670-0128PUS1
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Takamitu MIKUNI et al.

Application No.: 10/582,985

Confirmation No.: 8826

Filed: June 15, 2006

Art Unit: 1794

For: THERMALLY CONDUCTIVE PRESSURE-
SENSITIVE ADHESIVE COMPOSITION,
THERMALLY CONDUCTIVE SHEET-FORM
MOLDED FOAM, AND PROCESS FOR
PRODUCING THE SAME

Examiner: H. Vo

REPLY TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In reply to the Restriction Requirement dated June 30, 2008, the following remarks are respectfully submitted in connection with the above-identified application.

This reply includes: Remarks.